Product Change Notification - RMES-09VPXZ131 (Printer Friendly)

Date:

08 Feb 2018

Product Category:

Ethernet PHYs

Notification subject:

CCB 2922 Final Notice: Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of ASE as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Pre Change:

Assembled at TICP using gold (Au) bond wire and CEL9200 molding compound material.

Post Change:

Assembled at ASE using gold (Au) bond wire and G631H molding compound material.

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc. (ASE)
Lead frame material	C7025	C7025
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Mold compound material	CEL9200	G631H

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying ASE as an additional assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
March 08, 2018 (date code:1810)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2017				->	**February 2018**				**March 2018**				
Workweek	14	15	16	17		05	06	07	08	09	10	11	12	13
Initial PCN Issue Date				X										
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date											X			

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
April 28, 2017: Issued initial notification.
May 8, 2017: Re-issued the initial notification to notify all affected customers.
February 08, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 08, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-09VPXZ131_Affected CPN.pdf
PCN_RMES-09VPXZ131_Qual Report.pdf
PCN_RMES-09VPXZ131_Affected CPN.xlsx

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